

# Tlam OptoTEC<sup>™</sup> Series OT08,32,F0T,0707 Thermoelectric Module

The Tlam OptoTEC<sup>™</sup> Series is a miniature thermoelectric module (TEM) that uses a thermally conductive dielectric with copper exteriors as substrates. This product line has improved heat spreading, higher mechanical integrity and can provide cost savings over standard ceramic based TEMs with similar form factors in high volume. This product series has been created for applications to stabilize the temperature of sensitive optical components in telecom, photonics, medical and consumer markets.

This product line is available in multiple configurations and surface finishing options. The Tlam OptoTEC<sup>™</sup> Series is designed for lower current and lower heat-pumping applications and are easily customizatable to accomodate alternate sizes, heat pumping capacities, pretinning, unique circuit patterns, or solder posts, however MOQ applies.

#### FEATURES **Rohs**

- Miniature geometric sizes
- Precise temperature control
- Reliable solid state operation
- No sound or vibration
- DC operation
- RoHS compliant

PERFORMANCE SPECIFICATIONS					
Hot Side Temperature (°C)	25	50			
Qmax (Watts)	1.7	1.9			
Delta Tmax (°C)	67	77			
Imax (Amps)	0.8	0.8			
Vmax (Volts)	3.7	4.1			
Module Resistance (ohms)	4.17	4.71			

#### **APPLICATIONS**

- Laser diodes
- CCD cameras
- Infrared (IR) sensors
- Pump lasers
- Crystal oscillators
- Optical transceivers

SUFFIX	THICKNESS (PRIOR TO TINNING)	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
22	0.114"± 0.005"	NA / NA	Pre-tinned	Pre-tinned	2.0"
GG	0.114"± 0.005"	NA / NA	Au plated	Au plated	2.0″

### **SEALING OPTION**

SUFFIX	SEALANT	COLOR	TEMP RANGE	DESCRIPTION
RT	RTV	White	-60 to 204 °C	Non-corrosive, silicone adhesive sealant
EP	Ероху	Black	-55 to 150 °C	Low density syntactic foam epoxy encapsulant

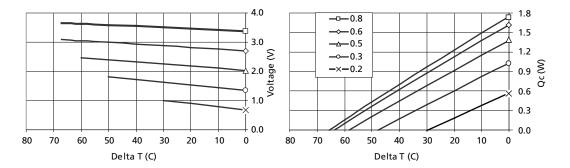
Americas: +1 888.246.9050 Europe: +46.31.704.67.57 Asia: +86.755.2714.1166

clv.customerpos@lairdtech.com www.lairdtech.com

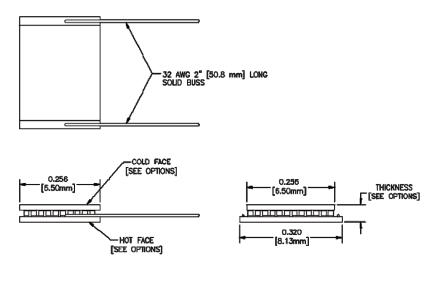


# Tlam OptoTEC<sup>™</sup> Series OT08,32,F0T,0707 Thermoelectric Module

### **PERFORMANCE CURVES**



## **MECHANICAL DRAWING**



Ceramic Material 96% Alumina Ceramics Solder Construction: 138°C, Bismuth Tin

#### **OPERATING TIPS**

- Max Operating Temperature: 80°C
- Do not exceed Imax or Vmax when operating module
- Reference assembly guidelines for recommended installation
- Solder tinning also available on metallized ceramics

THR-DS-OT08,32,F0T,0707,11,W2.25 0913

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials prests with the end uses, since Laird Technologies and its agents cannot be aware of all potential uses. Laird Technologies materials prests with the end uses, since Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products for any specific or general uses. Laird Technologies, shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are as oblig products for any specific or general uses. Laird Technologies, shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are as oblig products for any specific or general uses. Laird Technologies, hind, and her marks are trade marks or registret ated marks or or generated and products for any specific damagent of the laird Technologies. Inc. All Rights Reserved. Laird, Laird Technologies, hind and her marks are trade marks or or generated take marks or or generated take marks or or generated take marks or generated take marks or generated take marks or any efficient technologies, hind. All Rights Reserved. Laird, Laird Technologies, hind and the property of third parties. Nothing herein provides a license under any Laird Technologies construction of the specific damagent of the laird Technologies here. The specific damagent of the laird Technologies here and the specific damagent of the laird Technologies here. The specific damagent of the laird here hore h